

Remarks

In the present Office Action, the Examiner rejected claims 37 through 41 under 35 U.S.C. 103(a) as being unpatentable US Patent 3,524,782 to Buske (hereinafter the '782 patent). The Examiner indicated that claims 2 through 28, 33 through 36, 42 and 43 are allowable, for which the Applicants express their appreciation.

By the present amendment, claim 37 now recites in more detail the relationship between the shipping label line of weakness and how such line of weakness cooperates with the adhesive layer, release layer and shipping label first and second plies to leave the adhesive layer exposed on the back of the first ply and the release layer exposed on front of the second ply. There is nothing in the '782 patent, which teaches a protection label over a coupon, that teaches or suggests this feature. At most, the '782 patent teaches a continuous web of a single type of label (specifically, a coupon) repeated along the length of the web, whereas the packing list of claim 37 includes two separate labels (a packing list and a shipping label) formed from multiple plies that through judicious use of release and adhesive layers allow the shipping label of claim 37 to be applied as a single ply label when affixed to an object while the packing list can be preserved as a dual-ply, dual-sided item.

Because the '782 patent is devoid of the presently-recited features, the Applicant submits that amended claim 37 is patentable thereover. Furthermore, since all of the dependent claims 38 through 41 place additional limitations on independent claim 37, the Applicant submits that they too are allowable over the '782 patent.

The Examiner is encouraged to contact the undersigned to resolve efficiently any formal matters or to discuss any aspects of the application or of this response.

Respectfully submitted,

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